

SN65HVD82 Robust RS-485 Transceiver

1 Features

- Bus I/O Protection
 - ± 16 -kV HBM Protection
 - ± 12 -kV IEC61000-4-2 Contact Discharge
 - +4-kV IEC61000-4-4 Fast Transient Burst
- Industrial Temperature Range -40°C to 85°C
- Large Receiver Hysteresis (60 mV Typical) for Noise Rejection
- Low-Power Consumption
 - $< 1\text{-}\mu\text{A}$ Standby Current
 - $< 1\text{-mA}$ Quiescent Current
- Signaling Rate Optimized for 250 kbps

2 Applications

- Electrical Meters
- Building Automation
- Industrial Networks
- Security Electronics

3 Description

This device has robust drivers and receivers for demanding industrial applications. The bus pins are robust to ESD events, with high levels of protection to Human-Body Model, Air-Gap Discharge, and Contact Discharge specifications.

The device combines a differential driver and a differential receiver, which operate from a single 5-V power supply. The driver differential outputs and the receiver differential inputs are connected internally to form a bus port suitable for half-duplex (two-wire bus) communication. The device features a wide common-mode voltage range making the device suitable for multi-point applications over long cable runs. The device is characterized from -40°C to 85°C .

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)
SN65HVD82	SOIC (8)	4.90 mm $\times$ 3.91 mm

(1) For all available packages, see the orderable addendum at the end of the datasheet.

Logic Diagram (Positive Logic)

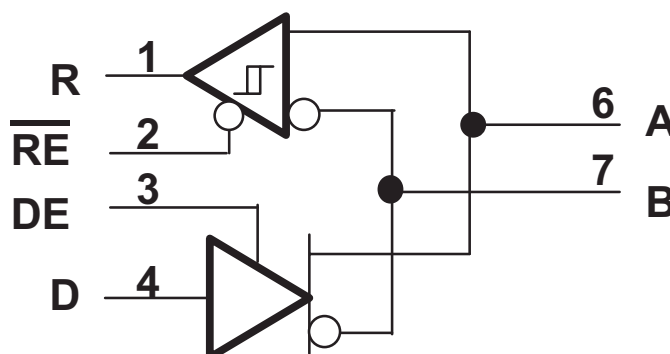


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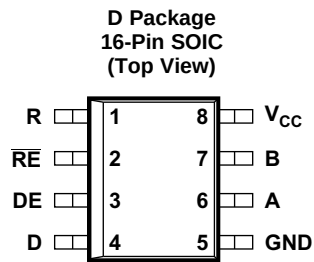
4 Revision History

Changes from Original (October 2012) to Revision A

Page

- Added *Pin Configuration and Functions* section, *ESD Ratings* table, *Feature Description* section, *Device Functional Modes*, *Application and Implementation* section, *Power Supply Recommendations* section, *Layout* section, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section **1**

5 Pin Configuration and Functions



Pin Functions

PIN		TYPE	DESCRIPTION
NAME	NO.		
A	6	Bus input/output	Driver output or receiver input (complementary to B)
B	7	Bus input/output	Driver output or receiver input (complementary to A)
D	4	Digital input	Driver data input
DE	3	Digital input	Driver enable, active high
GND	5	Reference potential	Local device ground
R	1	Digital output	Receive data output
RE	2	Digital input	Receiver enable, active low
V _{CC}	8	Supply	4.5-V to 5.5-V supply

6 Specifications

6.1 Absolute Maximum Ratings⁽¹⁾

		MIN	MAX	UNIT
V _{CC}	Supply voltage	−0.5	7	V
	Voltage range at A or B Inputs	−18	18	V
	Input voltage range at any logic pin	−0.3	5.7	V
	Voltage input range, transient pulse, A and B, through 100Ω	−100	100	V
	Receiver output current	−24	24	mA
T _J	Junction temperature		170	°C
	Continuous total power dissipation	See Thermal Information		
T _{STG}	Storage temperature	−65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

6.2 ESD Ratings

		VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±4000
		Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	±1500
		Machine model (MM), JEDEC Standard 22	±400
		IEC 61000-4-2 ESD (Contact Discharge)	±12000
		IEC 60749-26 ESD (Human Body Model)	±16000
		IEC 61000-4-4 EMC (Fast Transient Burst Immunity)	±4000

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.5	5	5.5	V
V_I	Input voltage at any bus terminal (separately or common mode) ⁽¹⁾	–7		12	V
V_{IH}	High-level input voltage (D, DE and $\overline{RE}$ inputs)	2		V_{CC}	V
V_{IL}	Low-level input voltage (D, DE and $\overline{RE}$ inputs)	0		0.8	V
V_{ID}	Differential input voltage (A and B inputs)	–12		12	V
I_O	Output current, Driver	–60		60	mA
	Output current, Receiver	–8		8	mA
R_L	Differential load resistance	54	60		Ω
C_L	Differential load capacitance		50		pF
$1/t_{UI}$	Signaling rate			250	kbps
T_A	Operating free-air temperature (see Application and Implementation section for thermal information)	–40		85	°C
T_J	Junction Temperature	–40		150	°C

(1) The algebraic convention, in which the least positive (most negative) limit is designated as minimum is used in this data sheet.

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾		SN65HVD82	UNIT
		D (SOIC)	
		8 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	116.1	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	60.8	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	57.1	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	13.9	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	56.5	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).

6.5 Electrical Characteristics

over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V _{OD}	Driver differential output voltage magnitude	See Figure 5, R _L = 60 Ω, 375 Ω on each output to –7 V to 12 V	1.5			V
		R _L = 54 Ω (RS-485)	1.5	2		V
		R _L = 100 Ω (RS-422)	2	2.5		V
Δ V _{OD}	Change in magnitude of driver differential output voltage	R _L = 54 Ω, C _L = 50 pF	–0.2	0	0.2	V
V _{OC(SS)}	Steady-state common-mode output voltage	Center of two 27-Ω load resistors	1	V _{CC} /2	3	V
ΔV _{OC}	Change in differential driver output common-mode voltage		–0.2	0	0.2	V
V _{OC(PP)}	Peak-to-peak driver common-mode output voltage			850		mV
C _{OD}	Differential output capacitance			8		pF
V _{IT+}	Positive-going receiver differential input voltage threshold		See ⁽¹⁾	–70	–20	mV
V _{IT–}	Negative-going receiver differential input voltage threshold		–200	–150	See ⁽¹⁾	mV
V _{HYS}	Receiver differential input voltage threshold hysteresis (V _{IT+} – V _{IT–})		40	60		mV
V _{OH}	Receiver high-level output voltage	I _{OH} = –8 mA	4	V _{CC} –0.3		V
V _{OL}	Receiver low-level output voltage	I _{OL} = 8 mA		0.2	0.4	V
I _I	Driver input, driver enable, and receiver enable input current		–2		2	μA
I _{OZ}	Receiver output high-impedance current	V _O = 0 V or V _{CC} , $\overline{RE}$ at V _{CC}	–10		10	μA
I _{OS}	Driver short-circuit output current	I _{OS} with V _A or V _B from –7 V to +12 V			150	mA
I _I	Bus input current (disabled driver)	V _{CC} = 4.5 to 5.5 V or V _{CC} = 0 V, DE at 0 V		75	125	μA
		V _I = 12 V V _I = –7 V	–100	–40		
I _{CC}	Supply current (quiescent)	Driver and Receiver enabled			900	μA
		Driver enabled, receiver disabled			650	
		Driver disabled, receiver enabled			650	
		Driver and receiver disabled		0.4	2	
	Supply current (dynamic)	See Typical Characteristics				

(1) Under any specific conditions, V_{IT+} is assured to be at least V_{HYS} higher than V_{IT–}.

6.6 Switching Characteristics

over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
DRIVER							
t _r , t _f	Driver differential output rise/fall time	R _L = 54 Ω, C _L = 50 pF, See Figure 7		400	700	1200	ns
t _{PHL} , t _{PLH}	Driver propagation delay			90	700	1000	ns
t _{SK(P)}	Driver pulse skew, t _{PHL} – t _{PLH}			25 200		ns	
t _{PHZ} , t _{PLZ}	Driver disable time		See Figure 8 and Figure 9	50 500		ns	
t _{PZH} , t _{PZL}	Driver enable time	Receiver enabled		500 1000		ns	
		Receiver disabled		3 9		μs	
RECEIVER							
t _r , t _f	Receiver output rise/fall time	C _L = 15 pF, See Figure 10		18 30		ns	
t _{PHL} , t _{PLH}	Receiver propagation delay time			85 195		ns	
t _{SK(P)}	Receiver pulse skew, t _{PHL} – t _{PLH}			1 15		ns	
t _{PLZ} , t _{PHZ}	Receiver disable time			50 500		ns	
t _{PZL(1)} , t _{PZH(1)}	Receiver enable time	Driver enabled, See Figure 11		20 130		ns	
t _{PZL(2)} , t _{PZH(2)}		Driver disabled, See Figure 12		2 8		μs	

6.7 Typical Characteristics

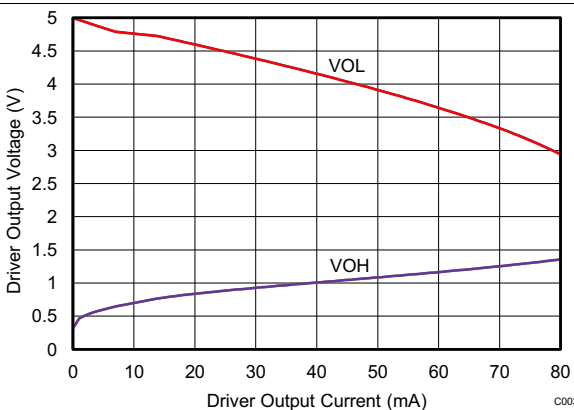


Figure 1. Driver Output Voltage vs Driver Output Current

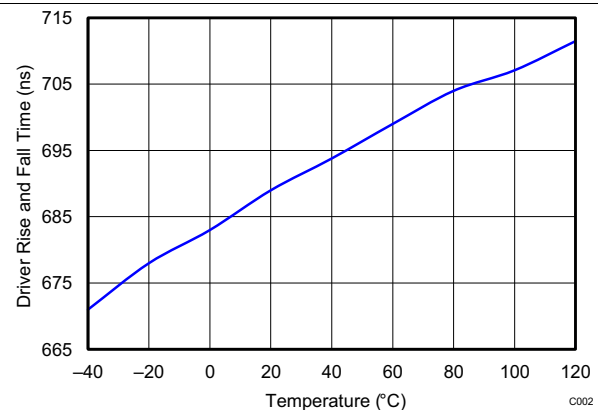


Figure 2. Driver Rise and Fall Time vs Temperature

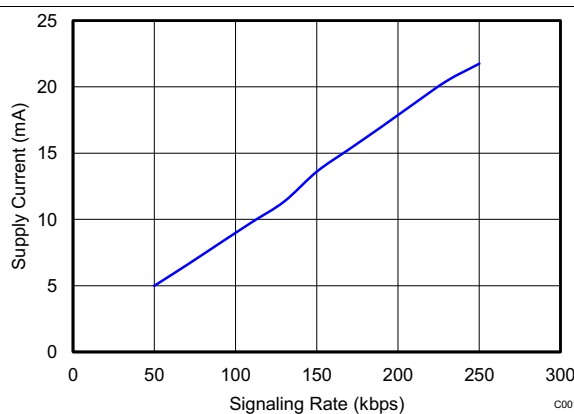


Figure 3. Supply Current vs Signaling Rate

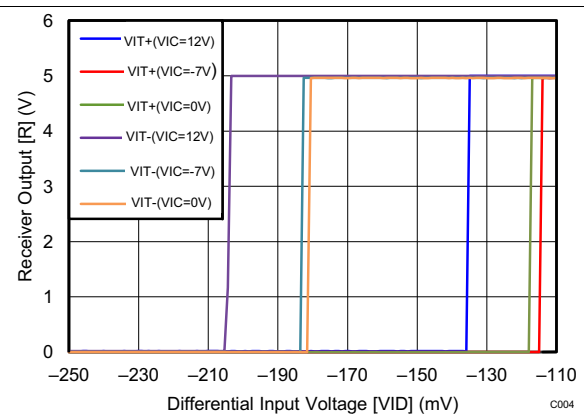
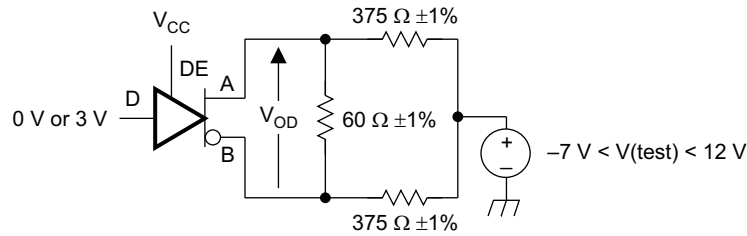


Figure 4. Receiver Output vs Differential Input Voltage

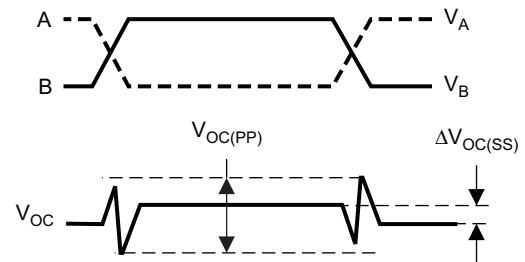
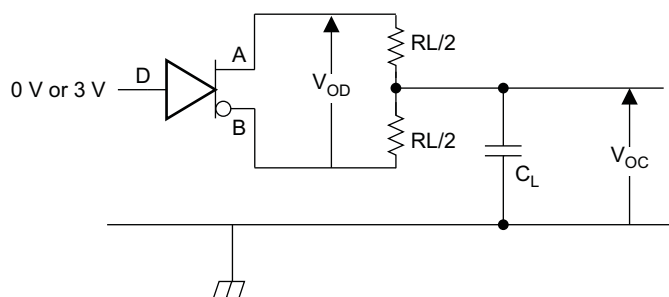
7 Parameter Measurement Information

Input generator rate is 100 kbps, 50% duty cycle, rise and fall times less than 6 nsec, output impedance 50 Ω .



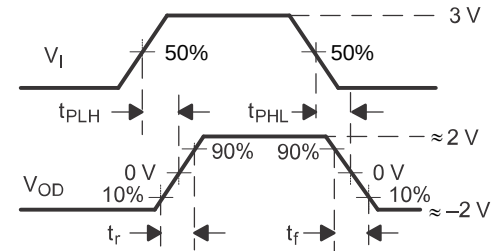
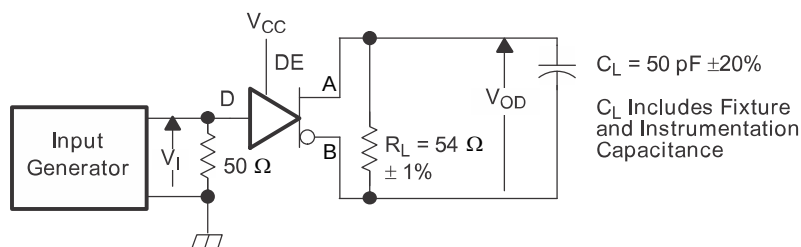
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Figure 5. Measurement of Driver Differential Output Voltage With Common-Mode Load



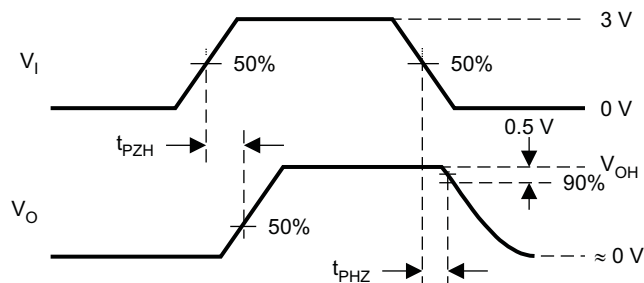
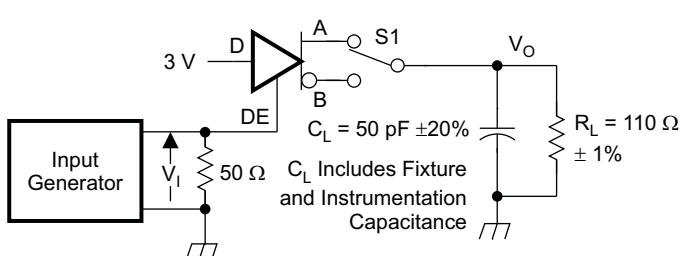
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Figure 6. Measurement of Driver Differential and Common-Mode Output With RS-485 Load



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Figure 7. Measurement of Driver Differential Output Rise and Fall Times and Propagation Delays



S0304-01

D at 3V to test non-inverting output, D at 0V to test inverting output.

Figure 8. Measurement of Driver Enable and Disable Times With Active High Output and Pull-Down Load

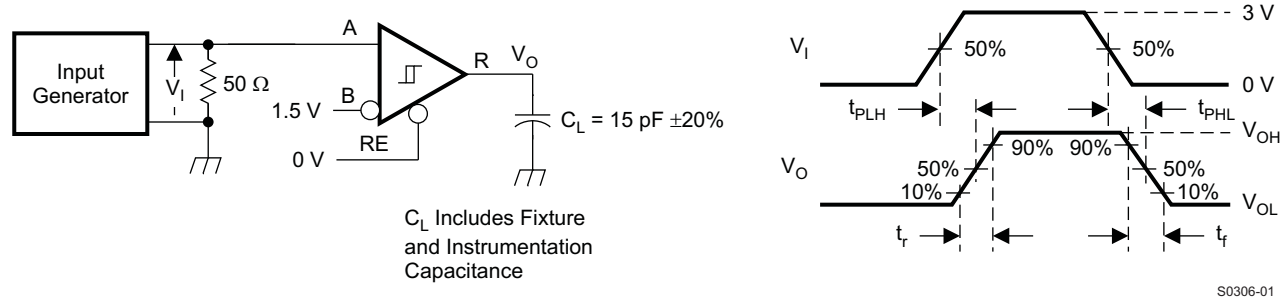
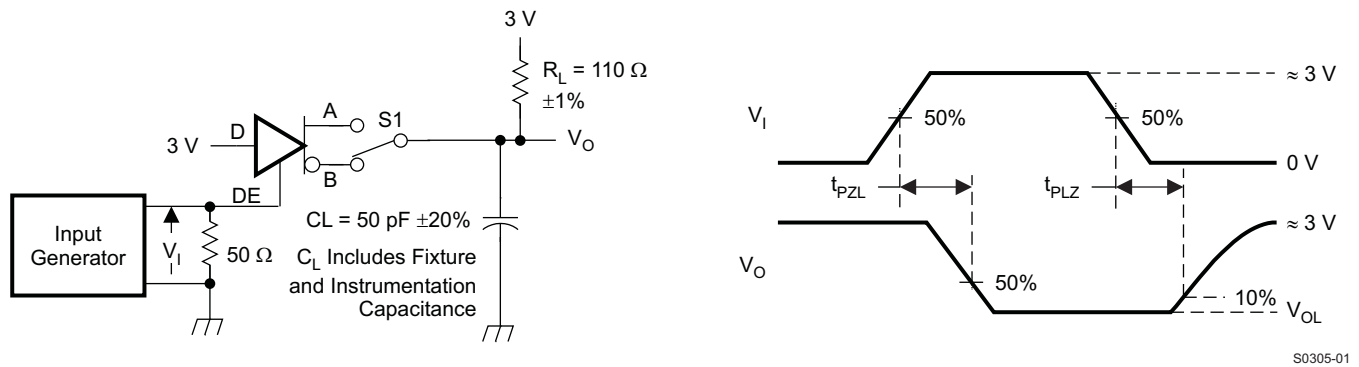
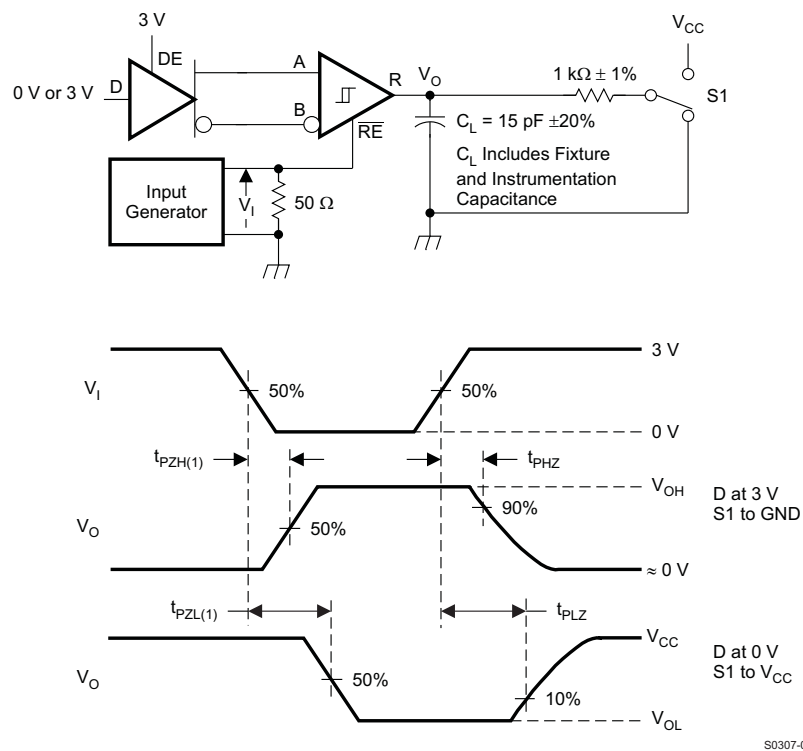
Parameter Measurement Information (continued)


Figure 10. Measurement of Receiver Output Rise and Fall Times and Propagation Delays



Parameter Measurement Information (continued)

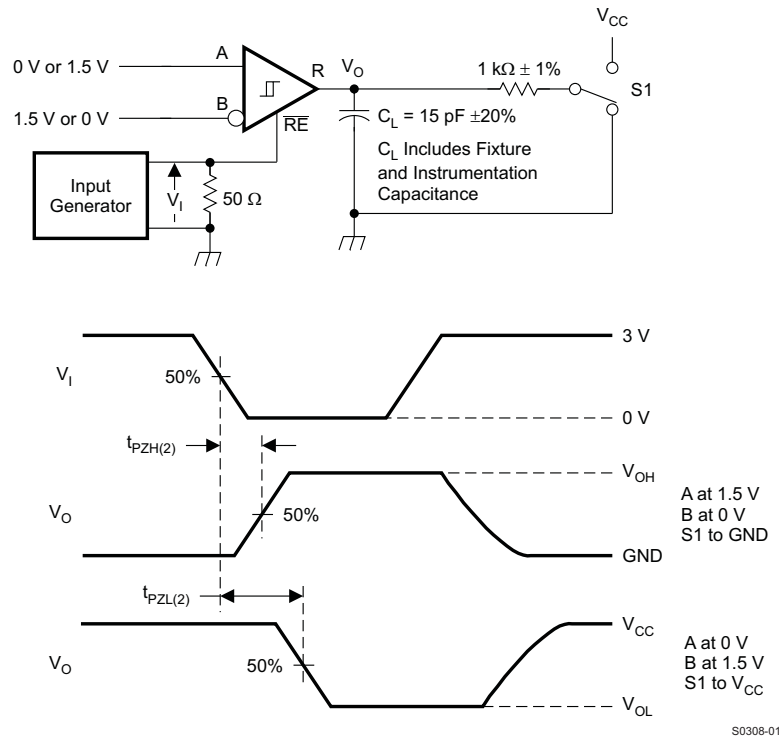


Figure 12. Measurement of Receiver Enable Times With Driver Disabled

8 Detailed Description

8.1 Overview

The SN65HVD82 device is a half-duplex RS-485 transceiver suitable for data transmission at rates up to 250 kbps over controlled-impedance transmission media (such as twisted-pair cabling). The device features a high level of internal transient protection, making it able to withstand up ESD strikes up to 12 kV (per IEC 61000-4-2) and EFT transients up to 4 kV (per IEC 61000-4-4) without incurring damage. Up to 256 units of SN65HVD82 may share a common RS-485 bus due to the device's low bus input currents. The device also features a low standby current consumption of 400 nA (typical).

8.2 Functional Block Diagram

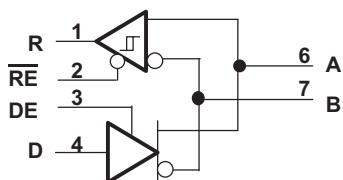


Figure 13. Logic Diagram (Positive Logic)

8.3 Feature Description

8.3.1 Receiver Failsafe

The differential receiver is *failsafe* to invalid bus states caused by:

- open bus conditions such as a disconnected connector
- shorted bus conditions such as cable damage shorting the twisted-pair together, or
- idle bus conditions that occur when no driver on the bus is actively driving

In any of these cases, the differential receiver will output a failsafe logic High state so that the output of the receiver is not indeterminate.

Receiver failsafe is accomplished by offsetting the receiver thresholds so that the “input indeterminate” range does not include zero volts differential. In order to comply with the RS-422 and RS-485 standards, the receiver output must output a High when the differential input V_{ID} is more positive than 200 mV, and must output a Low when the V_{ID} is more negative than –200 mV. The receiver parameters which determine the failsafe performance are V_{IT+} and V_{IT-} and V_{HYS} . As seen in the Electrical Characteristics table, differential signals more negative than –200 mV will always cause a Low receiver output. Similarly, differential signals more positive than 200 mV will always cause a High receiver output.

When the differential input signal is close to zero, it will still be above the V_{IT+} threshold, and the receiver output will be High. Only when the differential input is more negative than V_{IT-} will the receiver output transition to a Low state. So the noise immunity of the receiver inputs during a bus fault condition includes the receiver hysteresis value V_{HYS} (the separation between V_{IT+} and V_{IT-}) as well as the value of V_{IT+} .

Signals which transition from positive to negative (or from negative to positive) will transition only once, ensuring no spurious bits.

8.3.2 Low-Power Standby Mode

When both the driver and receiver are disabled (DE transitions to a low state and RE transitions to a high state) the device enters standby mode. If the enable inputs are in this state for a brief time (e.g. less than 100 ns), the device does not enter standby mode. This prevents inadvertently entering standby mode during driver/receiver enabling. Only when the enable inputs are held in this state a sufficient duration (e.g. for 300 ns or more), the device is assured to be in standby mode. In this low-power standby mode, most internal circuitry is powered down, and the steady-state supply current is typically less than 400 nA. When either the driver or the receiver is re-enabled, the internal circuitry becomes active.

8.4 Device Functional Modes

Table 1. Driver Function Table

INPUT	ENABLE	OUTPUTS		
D	DE	A	B	
H	H	H	L	Actively drive bus High
L	H	L	H	Actively drive bus Low
X	L	Z	Z	Driver disabled
X	OPEN	Z	Z	Driver disabled by default
OPEN	H	H	L	Actively drive bus High by default

Table 2. Receiver Function Table

DIFFERENTIAL INPUT	ENABLE	OUTPUT	
$V_{ID} = V_A - V_B$	RE	R	
$V_{IT+} < V_{ID}$	L	H	Receive valid bus High
$V_{IT-} < V_{ID} < V_{IT+}$	L	?	Indeterminate bus state
$V_{ID} < V_{IT-}$	L	L	Receive valid bus Low
X	H	Z	Receiver disabled
X	OPEN	Z	Receiver disabled by default
Open-circuit bus	L	H	Fail-safe high output
Short-circuit bus	L	H	Fail-safe high output
Idle (terminated) bus	L	H	Fail-safe high output

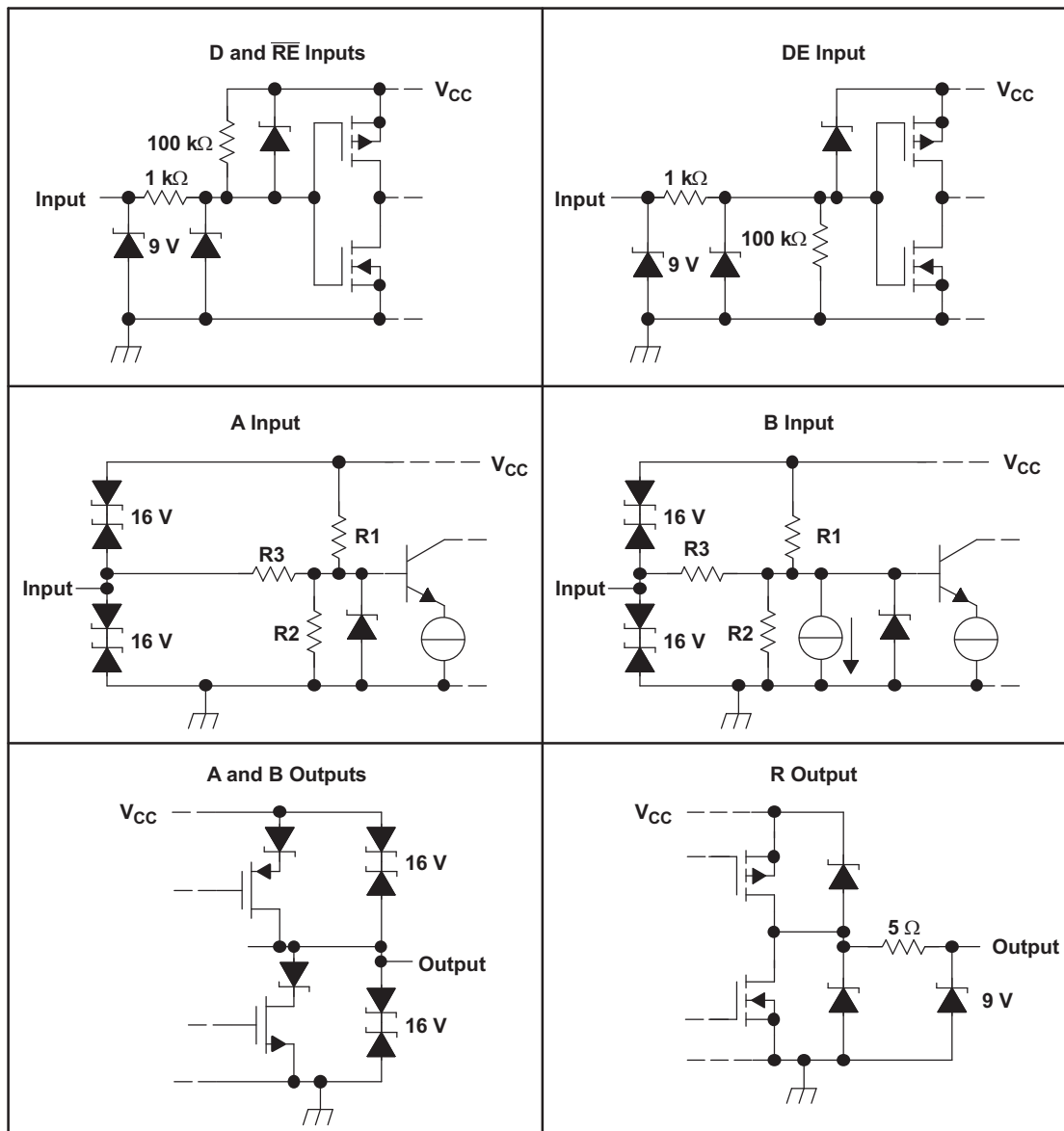


Figure 14. Equivalent Input and Output Schematic Diagrams

9 Application and Implementation

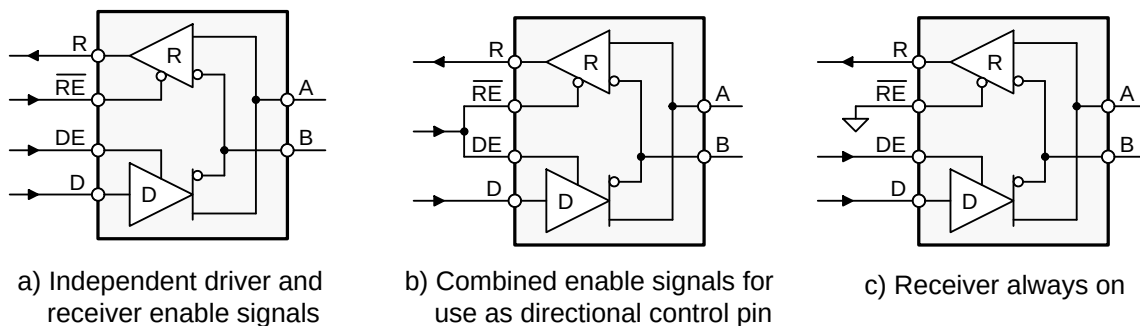
NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

9.1.1 Device Configuration

The SN65HVD82 is a half-duplex, 250-kbps, RS-485 transceiver operating from a single 5-V supply. The driver and receiver enable pins allow for the configuration of different operating modes.



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Figure 15. SN65HVD82 Transceiver Configurations

Using independent enable lines provides the most flexible control as it allows for the driver and the receiver to be turned on and off individually. While this configuration requires two control lines, it allows for selective listening into the bus traffic, whether the driver is transmitting data or not.

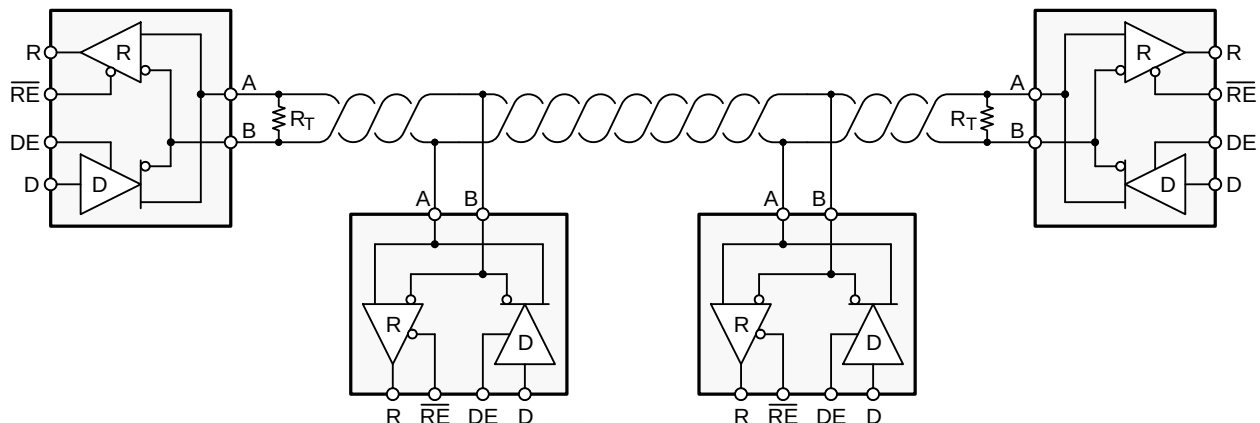
Combining the enable signals simplifies the interface to the controller by forming a single, direction-control signal. Thus, when the direction-control line is high, the transceiver is configured as a driver, while for a low the device operates as a receiver.

Tying the receiver-enable to ground and controlling only the driver-enable input, also uses one control line only. In this configuration a node not only receives the data from the bus, but also the data it sends and thus can verify that the correct data have been transmitted.

9.1.2 Bus – Design

An RS-485 bus consists of multiple transceivers connecting in parallel to a bus cable. To eliminate line reflections, each cable end is terminated with a termination resistor, R_T , whose value matches the characteristic impedance, Z_0 , of the cable. This method, known as parallel termination, allows for higher data rates over longer cable length.

Application Information (continued)



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Figure 16. Typical RS-485 Network with SN65HVD82 Transceivers

Common cables used are unshielded twisted pair (UTP), such as low-cost CAT-5 cable with $Z_0 = 100 \, \Omega$, and proper RS-485 cable with $Z_0 = 120 \, \Omega$.

Line measurements have shown that making R_T by up to 10% larger than Z_0 improves signal quality. Typical cable sizes are AWG 22 and AWG 24.

The theoretical maximum bus length is assumed with 4000 ft or 1200 m, and represents the length of an AWG 24 cable whose cable resistance approaches the value of the termination resistance, thus reducing the bus signal by half or 6 dB.

The theoretical maximum number of bus nodes is determined by the ratio of the RS-485 specified maximum of 32 unit loads (UL) and the actual unit load of the applied transceiver. For example, the SN65HVD82 is a 1/8 UL transceiver. Dividing 32 UL by 1/8 UL yields 256 transceivers that can be connected to one bus.

9.1.3 Cable-Length Versus Data Rate

There is an inverse relationship between data rate and cable length. That is, the higher the data rate the shorter the cable and conversely the lower the data rate the longer the cable. While most RS-485 systems utilize data rates between 10 kbps and 100 kbps, applications such as e-metering often operate at rates of up to 250 kbps even at distances of 4000 feet and above. This is possible by allowing for small signal jitter of up to 5 or 10%.

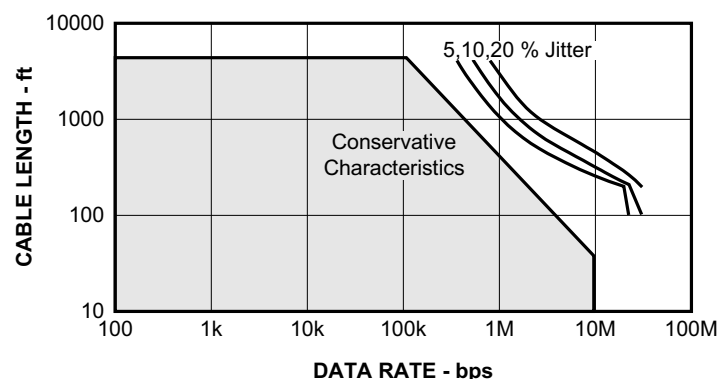


Figure 17. Cable Length vs Data Rate Characteristic

Application Information (continued)

9.1.4 Stub – Length

When connecting a node to the bus, the distance between the transceiver inputs and the cable trunk, known as the stub, should be as short as possible. The reason for this is that a stub presents a non-terminated piece of bus line which can introduce reflections if too long. As a rule of thumb the electrical length or round-trip delay of a stub should be less than one tenth of the driver's rise time, thus leading to a maximum physical stub length of: $L_{Stub} \leq 0.1 \times t_r \times v \times c$, with t_r as the driver's 10/90 rise time, c as the speed of light (3×10^8 m/s or 9.8×10^8 ft/s), and v as the signal velocity of the cable ($v = 78\%$) or trace ($v = 45\%$) as a factor of c .

Thus, for the SN65HVD82 with a minimum rise time of 400 ns the maximum *cable* stub length yields $L_{Stub} \leq 0.1 \times 400 \times 10^{-9} \times 3 \times 10^8 \times 0.78 = 9.4$ m or 30.6 ft.

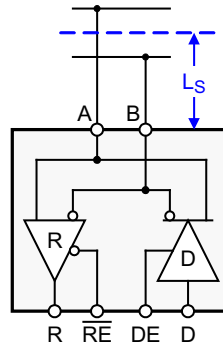


Figure 18. Stub Length

9.1.5 3-V to 5-V Interface

Interfacing the SN65HVD82 to a 3-V controller is easy. Because the 5-V logic inputs of the transceiver accept 3-V input signals they can be directly connected to the controller I/O. The 5-V receiver output, R, however must be level-shifted via a Schottky diode and a 10-kV resistor to connect to the controller input. When R is high, the diode is reverse biased and the controller supply potential lies at the controller input. When R is low, the diode is forward biased and conducts. In this case only the diode forward voltage of 0.2 V lies at the controller input.

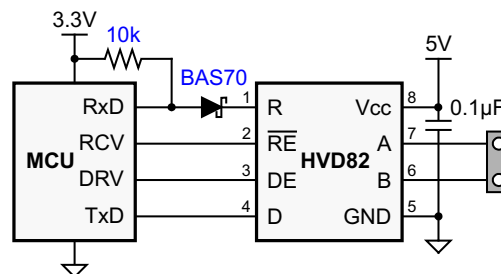


Figure 19. 3V–5V Interface

9.1.6 Noise Immunity

The input sensitivity of a standard RS-485 transceiver is ± 200 mV. When the differential input voltage, V_{ID} , is greater than +200 mV, the receiver output turns high, for $V_{ID} \leq 200$ mV the receiver outputs low. Bus voltages in between these levels can cause the receiver output to go high, or low, or even toggle between logic states. Small bus voltages however occur every time during the bus access hand-off from one driver to the next as the low-impedance termination resistors reduce the bus voltage to zero. To prevent receiver output toggling during bus idling, and thus increasing noise immunity, external bias resistors must be applied to create a bus voltage that is greater than the input sensitivity plus any expected differential noise.

Application Information (continued)

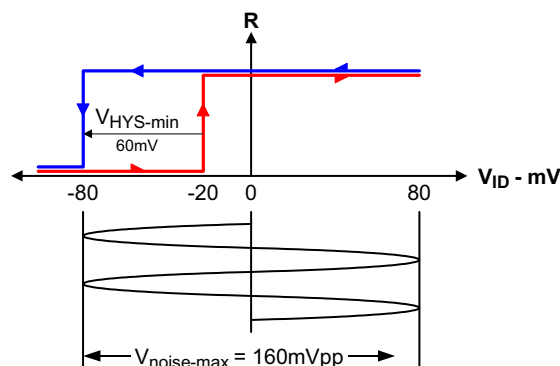
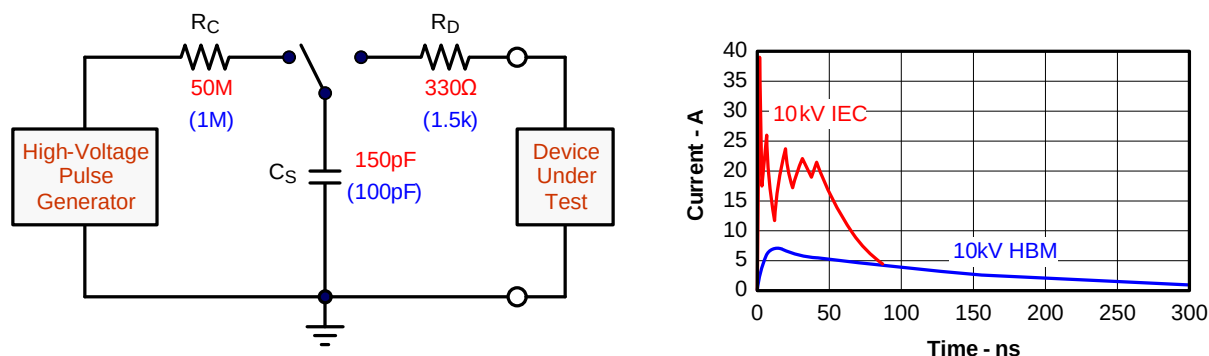


Figure 20. SN65HVD82 Noise Immunity

The SN65HVD82 transceiver circumvents idle-bus and differential noise issues by providing a positive input threshold of -20 mV and a typical hysteresis of 60 mV . In the case of an idle-bus condition therefore, a differential noise voltage of up to 160 mV_{pp} can be present without causing the receiver output to change states from high to low. This increased noise immunity eliminates the need for idle-bus failsafe bias resistors and allows for long haul data transmissions in noisy environment.

9.1.7 Transient Protection

The bus terminals of the SN65HVD82 transceiver family possess on-chip ESD protection against $\pm 15\text{ kV}$ human body model (HBM) and $\pm 12\text{ kV}$ IEC61000-4-2 contact discharge. As stated in the IEC 61000-4-2 standard, contact discharge is the preferred test method; although IEC air-gap testing is less repeatable than contact testing, air discharge protection levels are inferred from the contact discharge test results. The IEC-ESD test is far more severe than the HBM-ESD test. The 50% higher charge capacitance, C_S , and 78% lower discharge resistance, R_D of the IEC-model produce significantly higher discharge currents than the HBM-model.



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Figure 21. HBM and IEC-ESD Models and Currents in Comparison

EFTs are usually caused by relay contact bounce or the interruption of inductive loads, while surge transients often results from lightning strikes (direct strike or induced voltages and currents due to an indirect strike), or the switching of power systems including load changes and short circuits switching. These transients are often encountered in industrial environments, such as factory automation and power-grid systems.

Application Information (continued)

Figure 22 compares the pulse-power of the EFT and surge transients with the power caused by an IEC-ESD transient. As can be seen the tiny blue blip in the bottom left corner of the left diagram represents the power of a 10-kV ESD transient, which already dwarfs against the significantly higher EFT power spike and certainly against the 500-V surge transient. This type of transient power is well representative for factory environments in industrial and process automation. The right diagram compares the enormous power of a 6-kV surge transient, which more likely occurs in e-metering applications of power generating and power grid systems, with the aforementioned 500-V surge transient. *Note that the unit of the pulse-power changes from kW to MW, thus making the power of the 500-V surge transient almost dropping off the scale.*

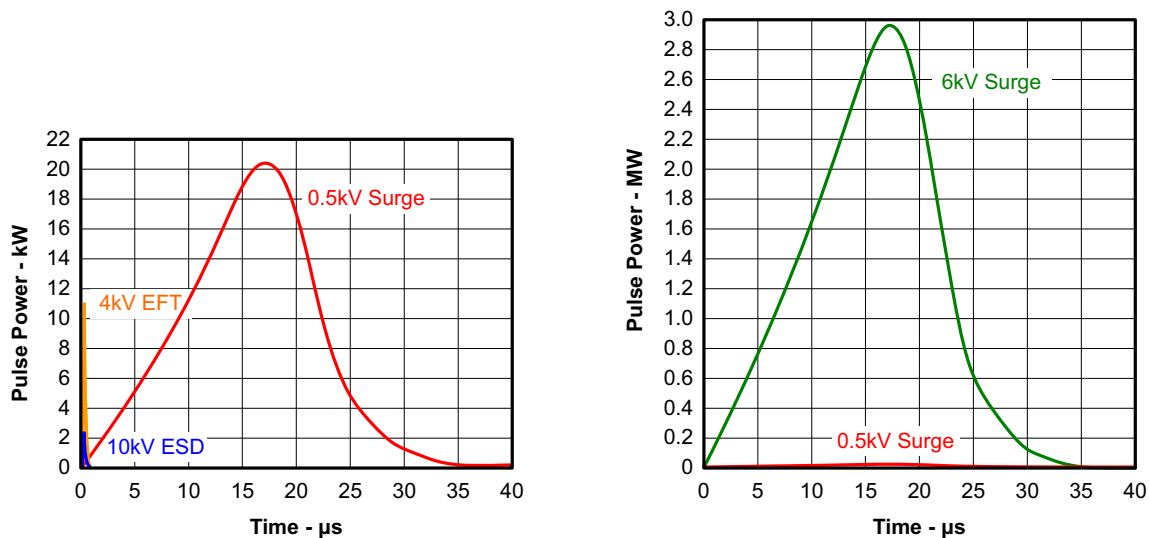


Figure 22. Power Comparison of ESD, EFT, and Surge Transients

In the case of surge transients, their long pulse duration and slowly decreasing pulse power signifies high energy content.

The electrical energy of a transient that is dumped onto the transceiver's internal protections cells is converted into thermal energy, or heat that literally fries the protection cells, thus destroying the transceiver. Figure 23 showcases the large differences in transient energies for single ESD, EFT, and surge transients as well as for an EFT pulse train, commonly applied during compliance testing.

Application Information (continued)

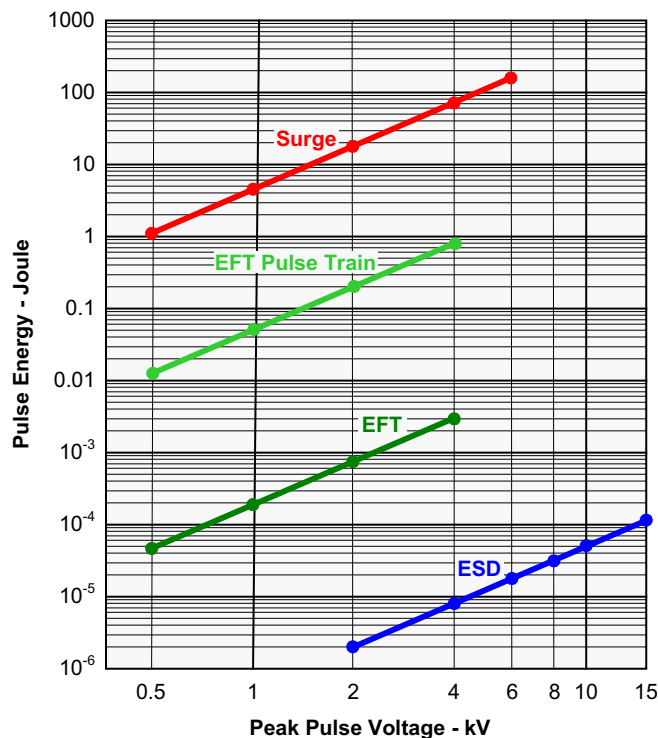
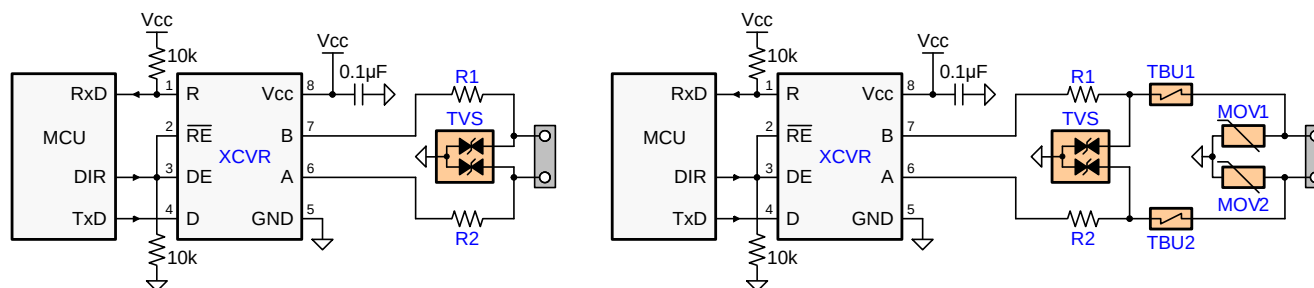


Figure 23. Comparison of Transient Energies

Figure 24 suggests two circuit designs providing protection against surge transients. Table 3 presents the associated bill of material.

Table 3. Bill of Materials

DEVICE	FUNCTION	ORDER NUMBER	MANUFACTURER
XCVR	3.3V, 250kbps RS-485 Transceiver	SN65HVD82D	TI
R1,R2	10Ω, Pulse-Proof Thick-Film Resistor	CRCW0603010RJNEAHP	Vishay
TVS	Bidirectional 400W Transient Suppressor	CDSOT23-SM712	Bourns
TBU1,TBU2	Bidirectional, 200mA Transient Blocking Unit	TBU-CA-065-200-WH	Bourns
MOV1,MOV2	200V, Metal-Oxide Varistor	MOV-10D201K	Bourns



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Figure 24. Transient Protection Against ESD, EFT, and Surge Transients

Both circuits are designed for 10-kV ESD and 4-kV EFT transient protection. The left however provides surge protection of ≥ 500 -V transients only, while the right protection circuits can withstand 5-kV surge transients.

9.2 Typical Application

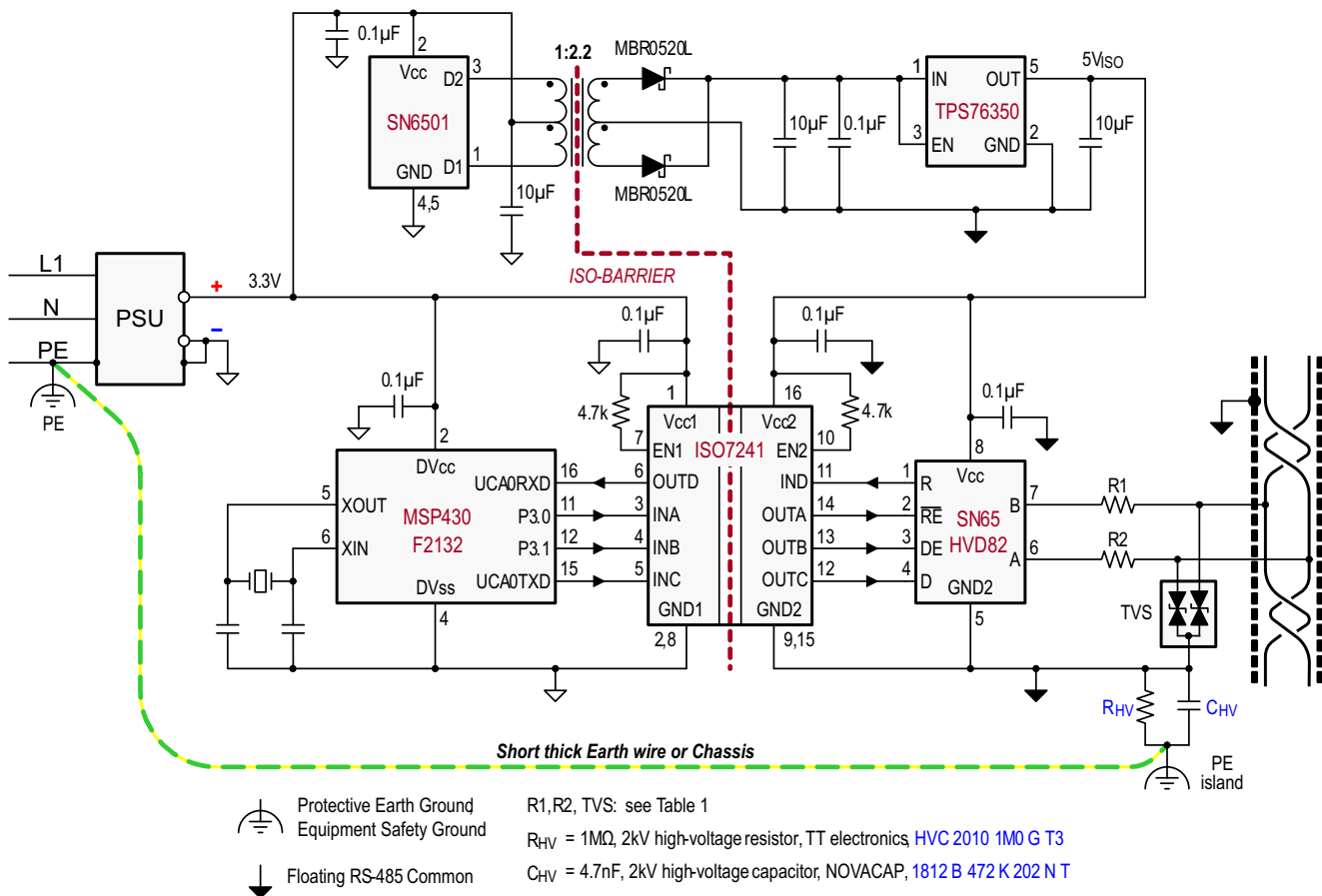


Figure 25. Isolated Bus Node With Transient Protection

9.2.1 Design Requirements

The following list outlines sample design requirements for the typical application example found in [Figure 25](#)

- RS-485-compliant bus interface (needs differential signal amplitude of at least 1.5 V under fully-loaded conditions – essentially, maximum number of nodes connected and with dual 120-Ω termination).
- Galvanic isolation of both signal and power supply lines.
- Able to withstand ESD transients up to 10 kV (per IEC 61000-4-2) and EFTs up to 4 kV (per IEC 61000-4-4).
- Full control of data flow on bus in order to prevent contention (for half-duplex communication).

9.2.2 Detailed Design Procedure

9.2.2.1 Isolated Bus Node Design

Many RS-485 networks use isolated bus nodes to prevent the creation of unintended ground loops and their disruptive impact on signal integrity. An isolated bus node typically includes a micro controller that connects to the bus transceiver via a multi-channel, digital isolator ([Figure 25](#)).

Power isolation is accomplished using the push-pull transformer driver SN6501 and a low-cost LDO, TPS76350

Signal isolation utilizes the quadruple digital isolator ISO7241. Notice that both enable inputs, EN1 and EN2, are pulled-up via 4.7-kΩ resistors to limit their input currents during transient events.

While the transient protection is similar to the one in [Figure 24](#) (left circuit), an additional high-voltage capacitor is used to divert transient energy from the floating RS-485 common further towards Protective Earth (PE) ground. This is necessary as noise transients on the bus are usually referred to Earth potential.

Typical Application (continued)

R_{VH} refers to a high-voltage resistor, and in some applications even a varistor. This resistance is applied to prevent charging of the floating ground to dangerous potentials during normal operation.

Occasionally varistors are used instead of resistors in order to rapidly discharge C_{HV} , if it is expected that fast transients might charge C_{HV} to high-potentials.

Note that the PE island represents a copper island on the PCB for the provision of a short, thick Earth wire connecting this island to PE ground at the entrance of the power supply unit (PSU).

In equipment designs using a chassis, the PE connection is usually provided through the chassis itself. Typically the PE conductor is tied to the chassis at one end while the high-voltage components, C_{HV} and R_{HV} , are connecting to the chassis at the other end.

9.2.3 Application Curve

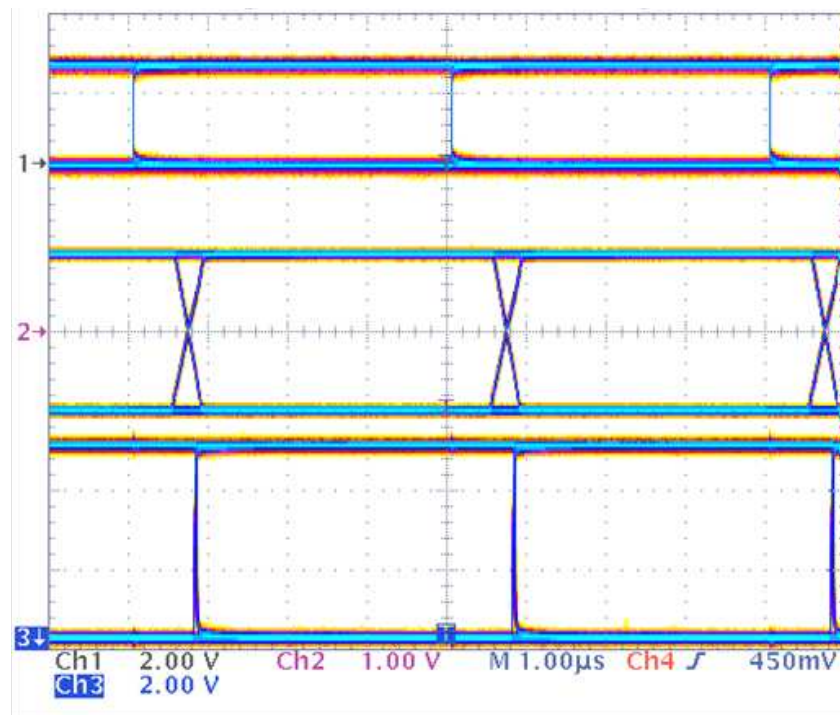


Figure 26. SN65GVD82 D Input (Top), Differential Output (Middle), and R Output (Bottom), 250 kbps Operation, PRBS Data Pattern

10 Power Supply Recommendations

To ensure reliable operation at all data rates and supply voltages, each supply should be decoupled with a 100-nF ceramic capacitor located as close to the supply pins as possible. This helps to reduce supply voltage ripple present on the outputs of switched-mode power supplies and also helps to compensate for the resistance and inductance of the PCB power planes.

11 Layout

11.1 Layout Guidelines

11.1.1 Design and Layout Considerations For Transient Protection

On-chip IEC-ESD protection is good for laboratory and portable equipment but never sufficient for EFT and surge transients occurring in industrial environments. Therefore robust and reliable bus node design requires the use of external transient protection devices.

Because ESD and EFT transients have a wide frequency bandwidth from approximately 3 MHz to 3 GHz, high-frequency layout techniques must be applied during PCB design.

In order for your PCB design to be successful start with the design of the protection circuit in mind.

1. Place the protection circuitry close to the bus connector to prevent noise transients from penetrating your board.
2. Use Vcc and ground planes to provide low-inductance. Note that high-frequency currents follow the path of least inductance and not the path of least impedance.
3. Design the protection components into the direction of the signal path. Do not force the transients currents to divert from the signal path to reach the protection device.
4. Apply 100-nF to 220-nF bypass capacitors as close as possible to the Vcc-pins of transceiver, UART, controller ICs on the board.
5. Use at least two vias for Vcc and ground connections of bypass capacitors and protection devices to minimize effective via-inductance.
6. Use 1-k Ω to 10-k Ω pullup or pulldown resistors for enable lines to limit noise currents in these lines during transient events.
7. Insert pulse-proof resistors into the A and B bus lines if the TVS clamping voltage is higher than the specified maximum voltage of the transceiver bus terminals. These resistors limit the residual clamping current into the transceiver and prevent it from latching up.
8. While pure TVS protection is sufficient for surge transients up to 1kV, higher transients require metal-oxide varistors (MOVs) which reduce the transients to a few hundred volts of clamping voltage, and transient blocking units (TBUs) that limit transient current to some 200 mA.

11.2 Layout Example

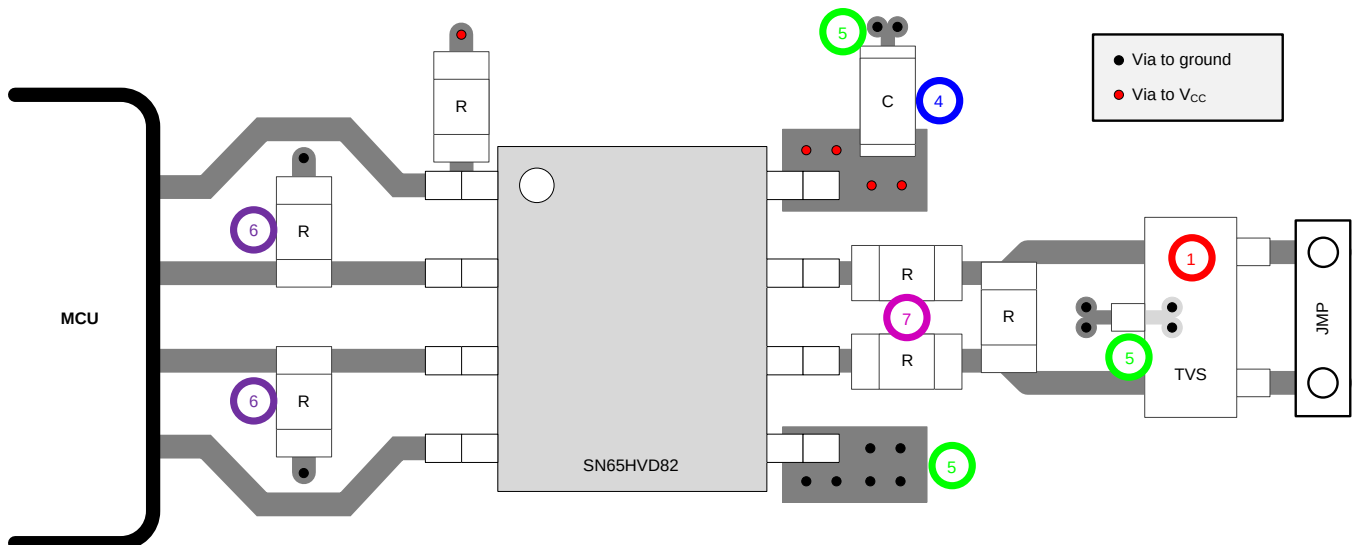


Figure 27. SN65HVD82 Layout Example

12 Device and Documentation Support

12.1 Device Support

12.1.1 Third-Party Products Disclaimer

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Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

12.3 Trademarks

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12.4 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

12.5 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN65HVD82D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HVD82	Samples
SN65HVD82DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HVD82	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

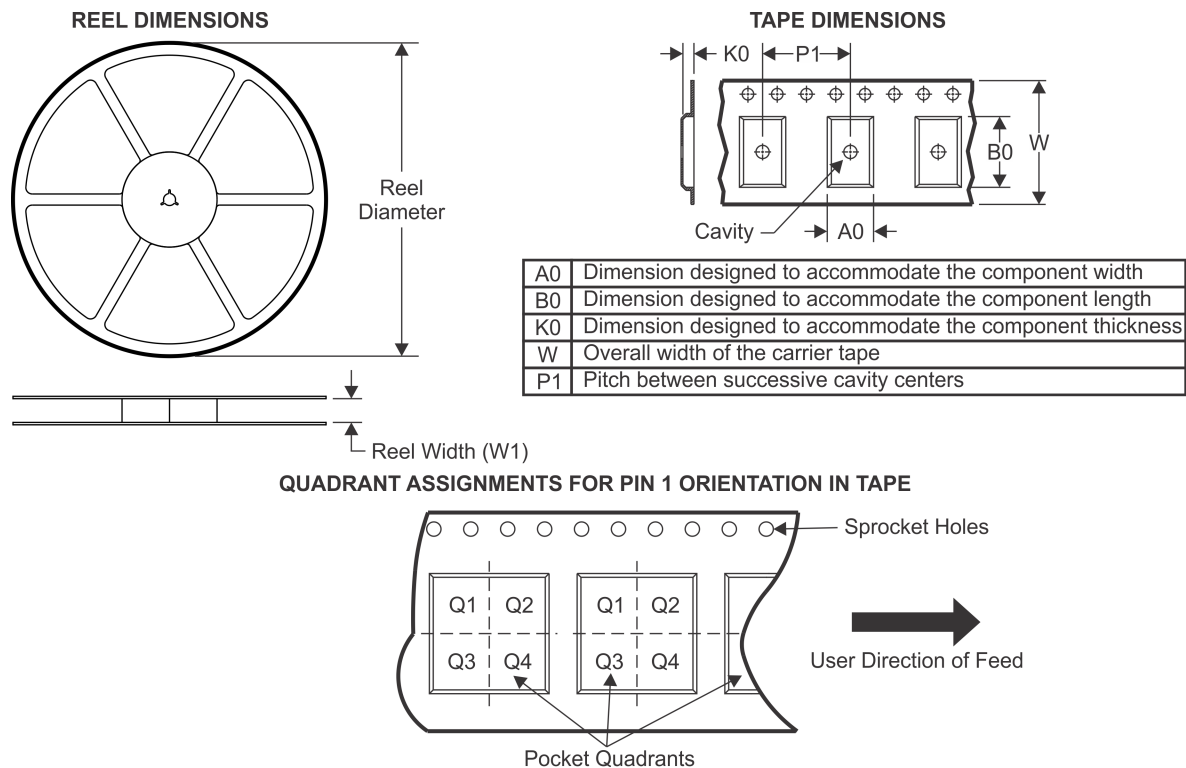
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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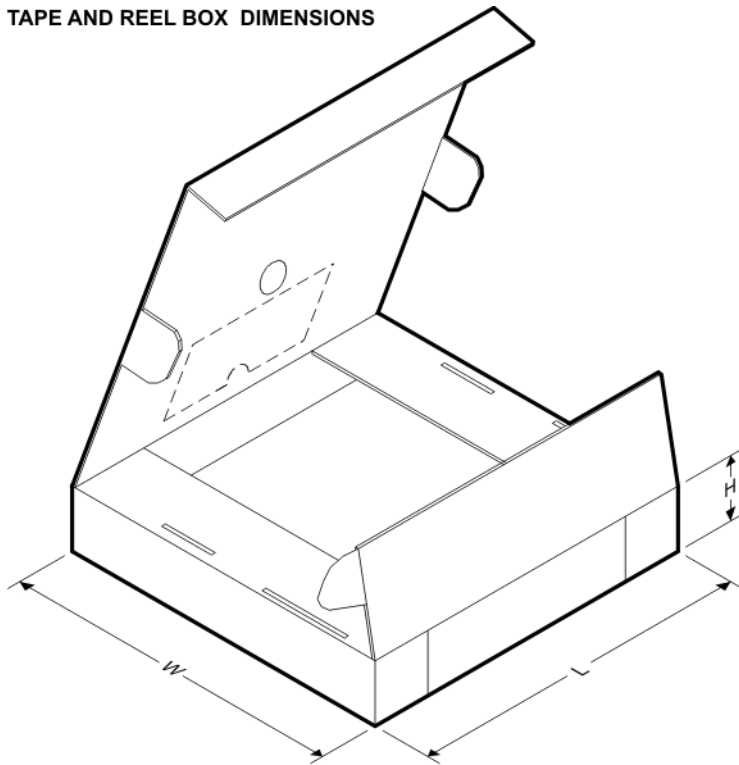
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TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65HVD82DR	SOIC	D	8	2500	330.0	12.5	6.4	5.2	2.1	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS

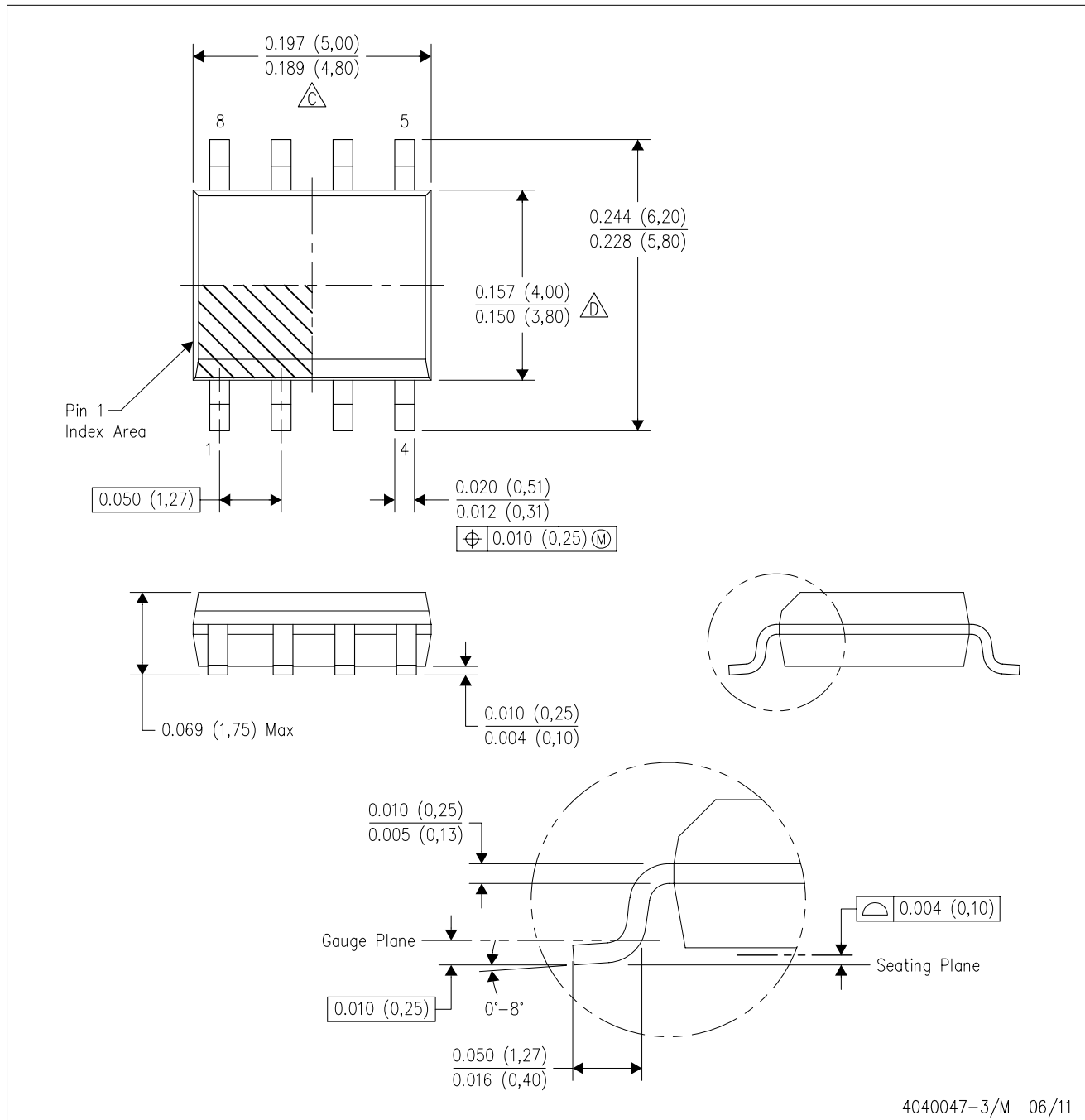


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN65HVD82DR	SOIC	D	8	2500	340.5	338.1	20.6

D (R-PDSO-G8)

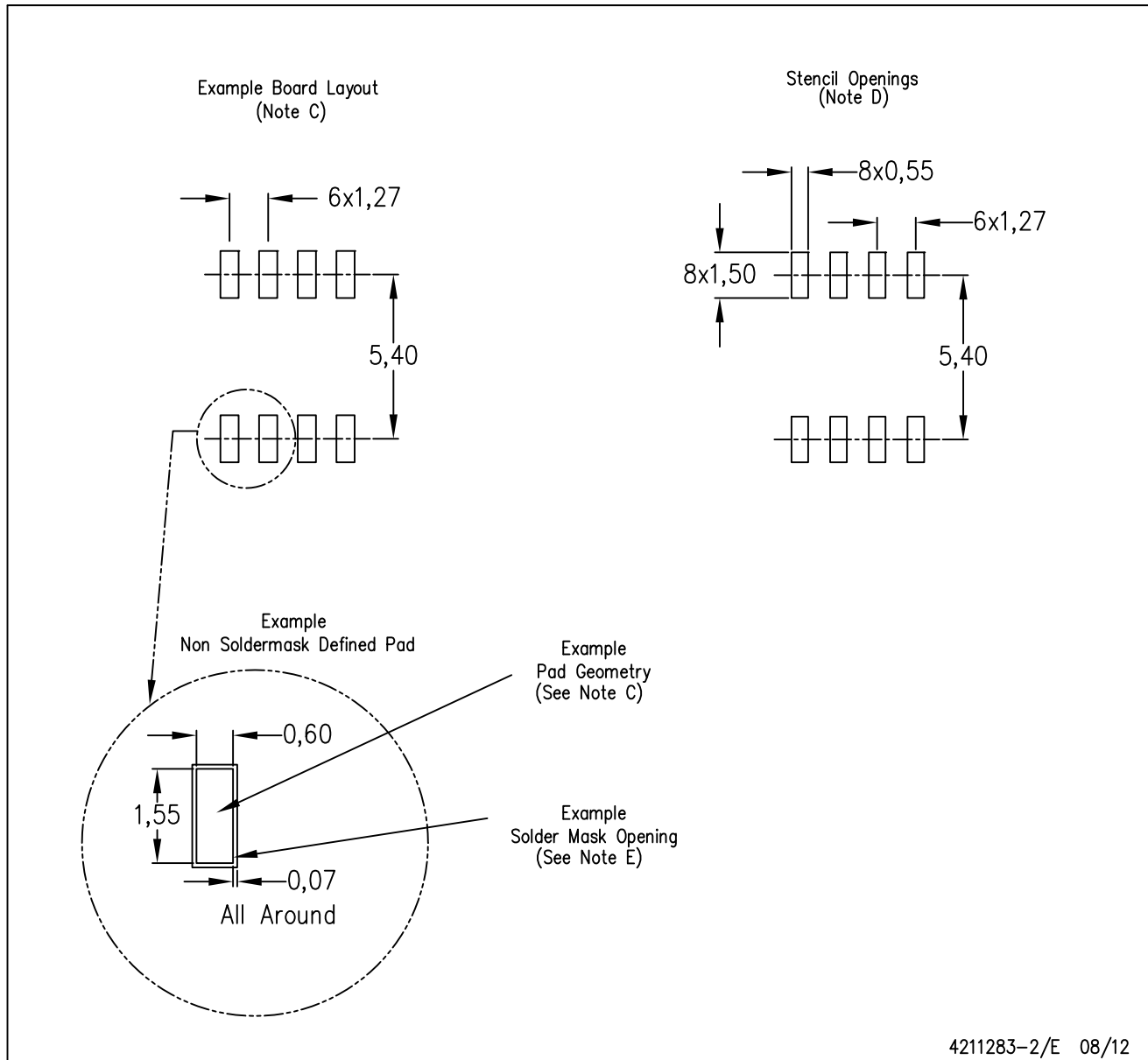
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AA.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
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 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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